

# SGH5N120RUFD

## Short Circuit Rated IGBT

### General Description

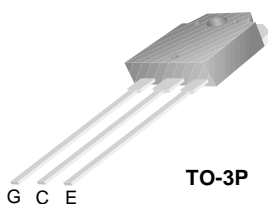
Fairchild's RUF D series of Insulated Gate Bipolar Transistors (IGBTs) provides low conduction and switching losses as well as short circuit ruggedness. The RUF D series is designed for applications such as motor control, uninterrupted power supplies (UPS) and general inverters where short circuit ruggedness is a required feature.

### Features

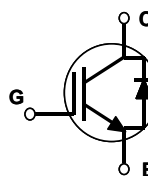
- Short circuit rated 10 $\mu$ s @ T<sub>C</sub> = 100°C, V<sub>GE</sub> = 15V
- High speed switching
- Low saturation voltage : V<sub>CE(sat)</sub> = 2.3 V @ I<sub>C</sub> = 5A
- High input impedance
- CO-PAK, IGBT with FRD : t<sub>rr</sub> = 55ns (typ.)

### Applications

AC & DC motor controls, general purpose inverters, robotics, and servo controls.



TO-3P



### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Description	SGH5N120RUFD	Units
V <sub>CES</sub>	Collector-Emitter Voltage	1200	V
V <sub>GES</sub>	Gate-Emitter Voltage	± 25	V
I <sub>C</sub>	Collector Current @ T <sub>C</sub> = 25°C	8	A
	Collector Current @ T <sub>C</sub> = 100°C	5	A
I <sub>CM(1)</sub>	Pulsed Collector Current	15	A
I <sub>F</sub>	Diode Continuous Forward Current @ T <sub>C</sub> = 100°C	5	A
I <sub>FM</sub>	Diode Maximum Forward Current	30	A
T <sub>SC</sub>	Short Circuit Withstand Time @ T <sub>C</sub> = 100°C	10	μs
P <sub>D</sub>	Maximum Power Dissipation @ T <sub>C</sub> = 25°C	74	W
	Maximum Power Dissipation @ T <sub>C</sub> = 100°C	30	W
T <sub>J</sub>	Operating Junction Temperature	-55 to +150	°C
T <sub>stg</sub>	Storage Temperature Range	-55 to +150	°C
T <sub>L</sub>	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds	300	°C

**Notes :**

(1) Repetitive rating : Pulse width limited by max. junction temperature

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
R <sub>θJC</sub> (IGBT)	Thermal Resistance, Junction-to-Case	--	1.68	°C/W
R <sub>θJC</sub> (DIODE)	Thermal Resistance, Junction-to-Case	--	2.4	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	--	40	°C/W

**Electrical Characteristics of the IGBT**  $T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
<b>Off Characteristics</b>						
$BV_{CES}$	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_C = 1mA$	1200	--	--	V
$\Delta BV_{CES}/\Delta T_J$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0V, I_C = 1mA$	--	0.6	--	$V/^\circ\text{C}$
$I_{CES}$	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$	--	--	1	mA
$I_{GES}$	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$	--	--	$\pm 100$	nA

**On Characteristics**

$V_{GE(th)}$	G-E Threshold Voltage	$I_C = 5mA, V_{CE} = V_{GE}$	3.5	5.5	7.5	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C = 5A, V_{GE} = 15V$	--	2.3	3.0	V
		$I_C = 8A, V_{GE} = 15V$	--	2.8	--	V

**Dynamic Characteristics**

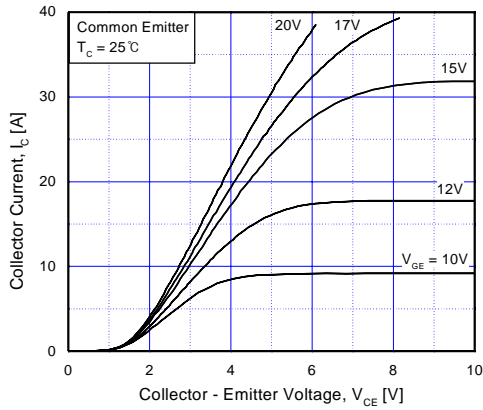
$C_{ies}$	Input Capacitance	$V_{CE} = 30V, V_{GE} = 0V,$ $f = 1MHz$	--	520	--	pF
$C_{oes}$	Output Capacitance		--	45	--	pF
$C_{res}$	Reverse Transfer Capacitance		--	16	--	pF

**Switching Characteristics**

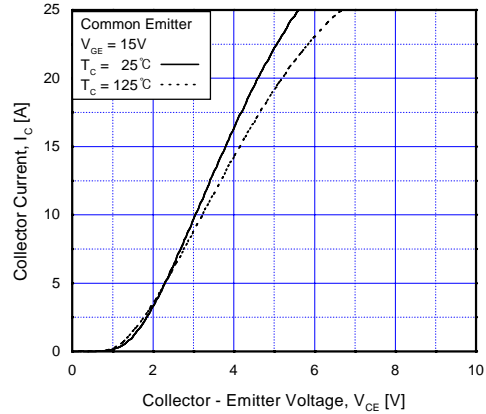
$t_{d(on)}$	Turn-On Delay Time	$V_{CC} = 600V, I_C = 5A,$ $R_G = 30\Omega, V_{GE} = 15V,$ Inductive Load, $T_C = 25^\circ\text{C}$	--	20	--	ns
$t_r$	Rise Time		--	60	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	50	90	ns
$t_f$	Fall Time		--	150	300	ns
$E_{on}$	Turn-On Switching Loss		--	0.35	--	mJ
$E_{off}$	Turn-Off Switching Loss		--	0.33	--	mJ
$E_{ts}$	Total Switching Loss	--	0.68	0.95	mJ	
$t_{d(on)}$	Turn-On Delay Time	$V_{CC} = 600V, I_C = 5A,$ $R_G = 30\Omega, V_{GE} = 15V,$ Inductive Load, $T_C = 125^\circ\text{C}$	--	20	--	ns
$t_r$	Rise Time		--	70	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	70	130	ns
$t_f$	Fall Time		--	200	400	ns
$E_{on}$	Turn-On Switching Loss		--	0.38	--	mJ
$E_{off}$	Turn-Off Switching Loss		--	0.50	--	mJ
$E_{ts}$	Total Switching Loss	--	0.88	1.28	mJ	
$T_{sc}$	Short Circuit Withstand Time	$V_{CC} = 600V, V_{GE} = 15V$ @ $T_C = 100^\circ\text{C}$	10	--	--	$\mu\text{s}$
$Q_g$	Total Gate Charge	$V_{CE} = 600V, I_C = 5A,$ $V_{GE} = 15V$	--	28	42	nC
$Q_{ge}$	Gate-Emitter Charge		--	3	5	nC
$Q_{gc}$	Gate-Collector Charge		--	13	18	nC
$L_e$	Internal Emitter Inductance	Measured 5mm from PKG	--	14	--	nH

**Electrical Characteristics of DIODE**  $T_C = 25^\circ\text{C}$  unless otherwise noted

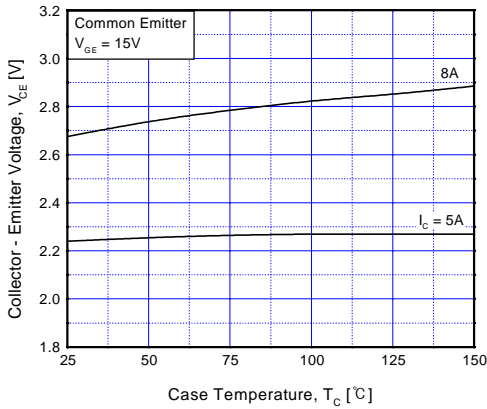
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units	
$V_{FM}$	Diode Forward Voltage	$I_F = 5A$	$T_C = 25^\circ\text{C}$	--	2.9	3.5	V
			$T_C = 100^\circ\text{C}$	--	2.7	--	
$t_{rr}$	Diode Reverse Recovery Time	$I_F = 5A$	$T_C = 25^\circ\text{C}$	--	55	100	ns
			$T_C = 100^\circ\text{C}$	--	70	--	
$I_{rr}$	Diode Peak Reverse Recovery Current	$dI/dt = 200A/\mu\text{s}$	$T_C = 25^\circ\text{C}$	--	5.0	7.0	A
			$T_C = 100^\circ\text{C}$	--	6.5	--	
$Q_{rr}$	Diode Reverse Recovery Charge		$T_C = 25^\circ\text{C}$	--	140	350	nC
			$T_C = 100^\circ\text{C}$	--	230	--	



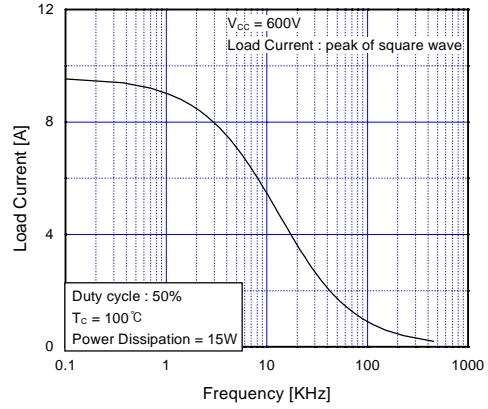
**Fig 1. Typical Output Characteristics**



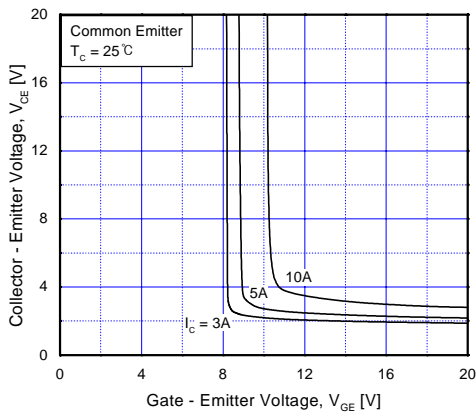
**Fig 2. Typical Saturation Voltage Characteristics**



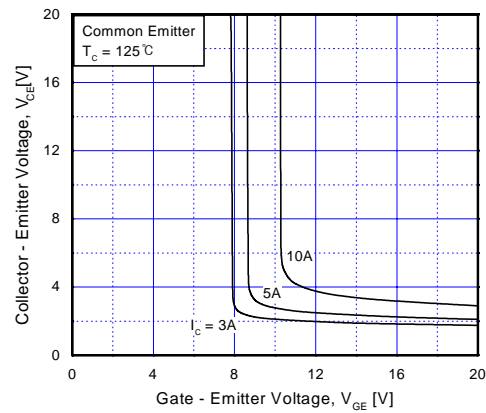
**Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level**



**Fig 4. Load Current vs. Frequency**



**Fig 5. Saturation Voltage vs.  $V_{GE}$**



**Fig 6. Saturation Voltage vs.  $V_{GE}$**

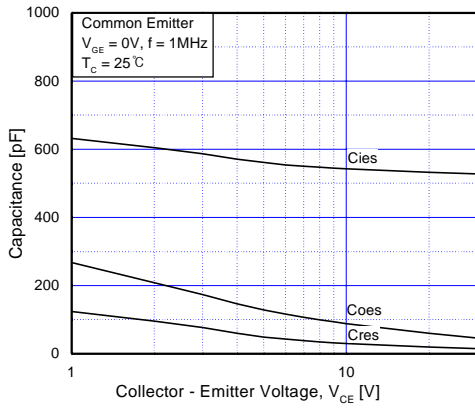


Fig 7. Capacitance Characteristics

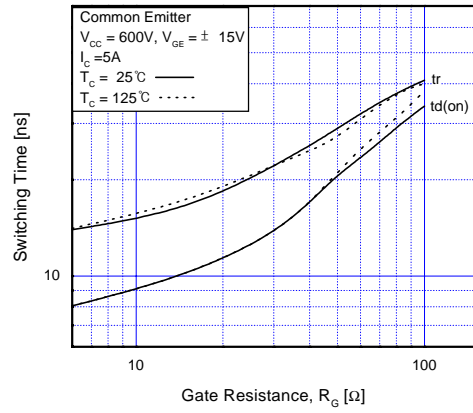


Fig 8. Turn-On Characteristics vs. Gate Resistance

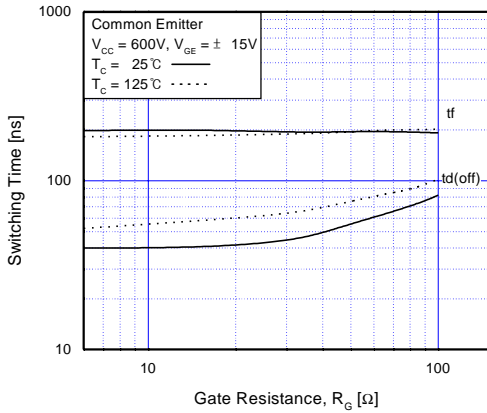


Fig 9. Turn-Off Characteristics vs. Gate Resistance

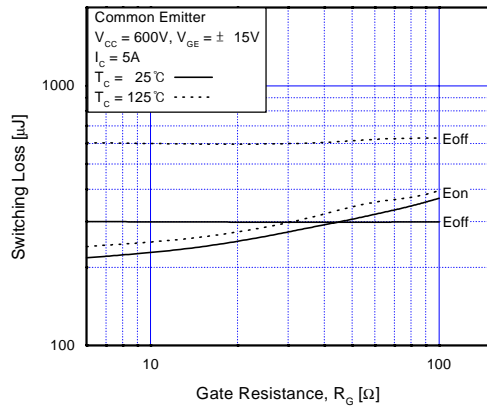


Fig 10. Switching Loss vs. Gate Resistance

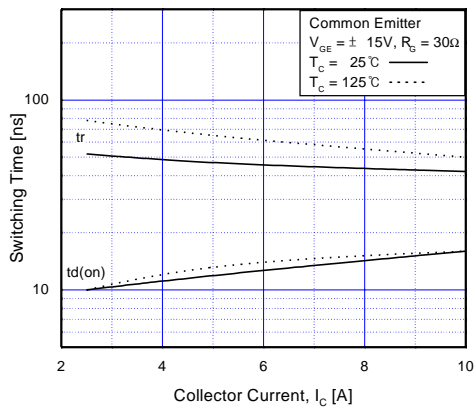


Fig 11. Turn-On Characteristics vs. Collector Current

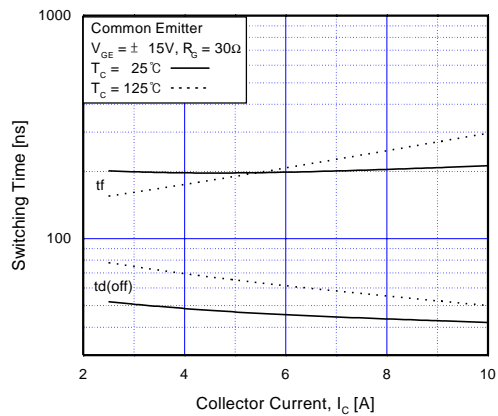
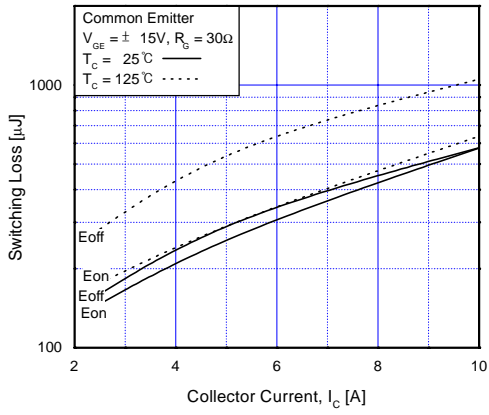
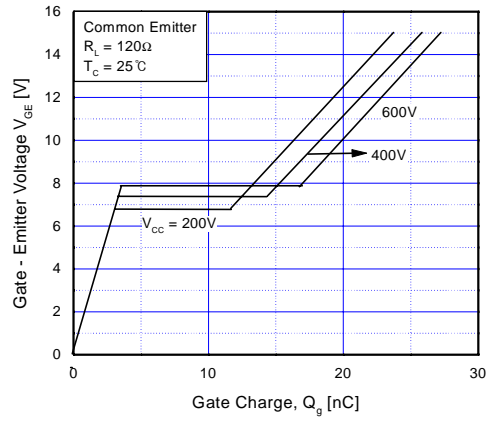


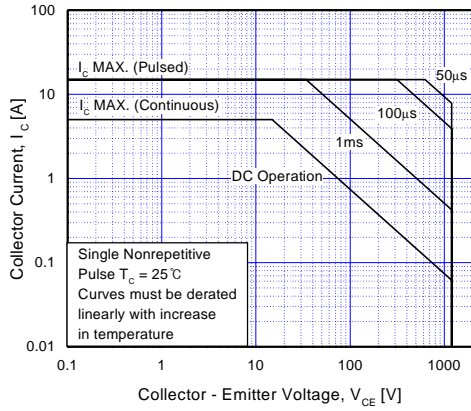
Fig 12. Turn-Off Characteristics vs. Collector Current



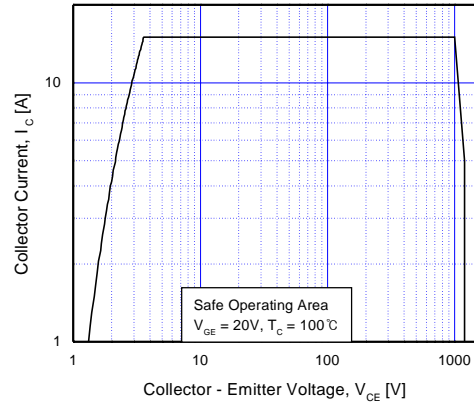
**Fig 13. Switching Loss vs. Collector Current**



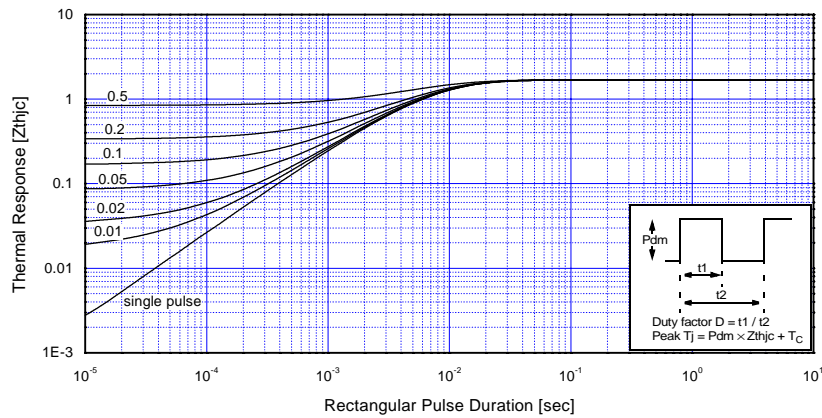
**Fig 14. Gate Charge Characteristics**



**Fig 15. SOA Characteristics**



**Fig 16. Turn-Off SOA**



**Fig 17. Transient Thermal Impedance of IGBT**

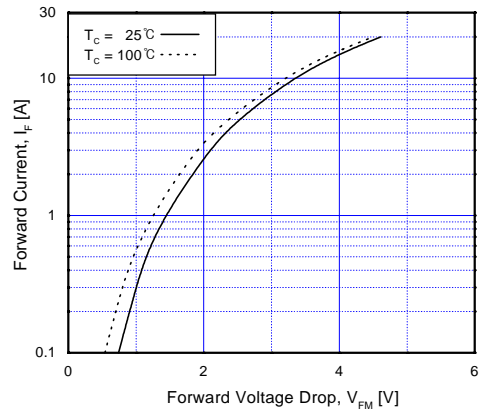


Fig 18. Forward Characteristics

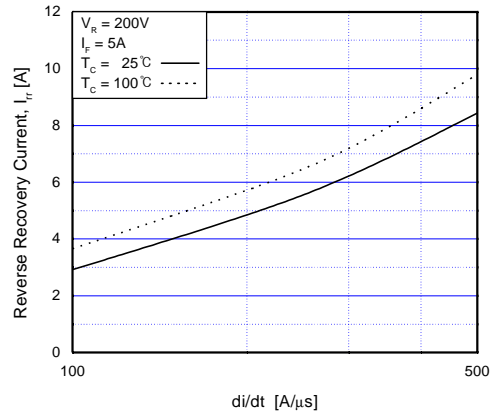


Fig 19. Reverse Recovery Current

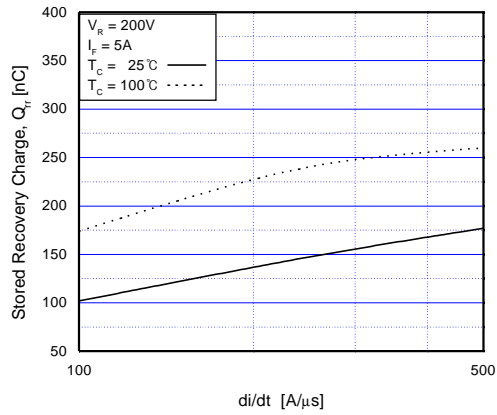


Fig 20. Stored Charge

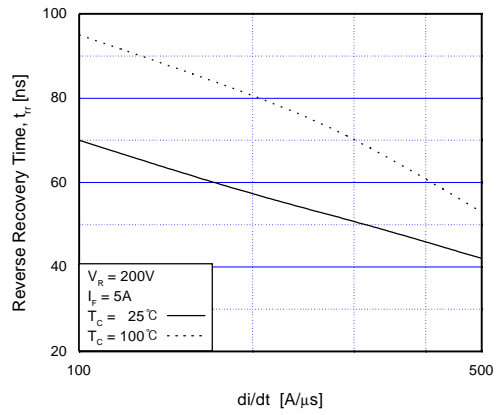
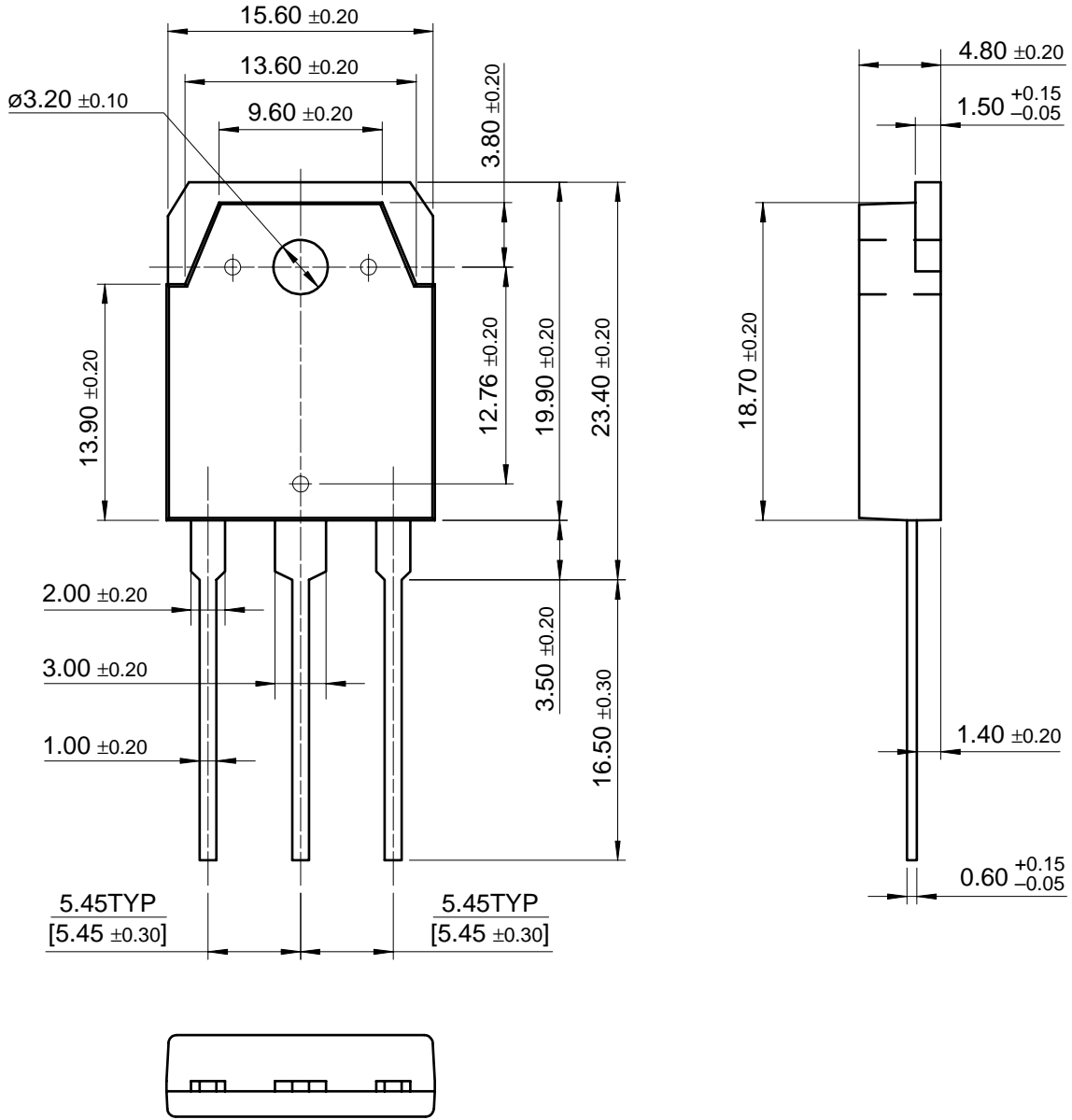


Fig 21. Reverse Recovery Time

Package Dimension

TO-3P (FS PKG CODE AF)



Dimensions in Millimeters

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